



## Advance Product Change Notification

201401001A

**Issue Date:** 10-Feb-2014

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# QUALITY

### Change Category

- |  |  |   |  |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking                | <input type="checkbox"/> Design                    |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification  |
| <input type="checkbox"/> Wafer Fab location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Test Location                  | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT23

### Details of this Planned Change

Scheduled changes affect product types in SOT23 package only.

(1) The bond wire material will be changed from gold (Au) to copper (Cu). Implementation of changes to copper wire as given by implementation date below.

Gold wire remains qualified for supply security reasons only.

(2) A second source mold compound supplier will be introduced for copper wire products.

Old product: Wire material is Au (with currently used mold compound suppliers)

Changed product: Wire material is Cu (with currently used first and new second source mold compound supplier) or Au (with currently used mold compound suppliers).

The design and materials of all other components will remain unchanged:

Die, die attach and lead frame.

Reliability qualification and full electrical characterization over temperature will be performed.

No change on thermal behavior or mechanical dimensions.

Electrical parameters remain unchanged (in specification and with the same distribution).

## Why do we Plan this Change

- (1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
- (2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM for associated types in SOT23 package.  
The second source supplier is already well established for NXP GA discrete semiconductor products.

## Identification of Affected Products

Changed products can be identified by date code after implementation.

## Product Availability

### Sample Information

Sample planning follows with the final PCN

### Production

Planned first shipment 15-Jul-2014

## Impact

No impact to the product's functionality anticipated.

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201005007F	27-Aug-2010		Change of bond wire material from gold to copper in SOT23 package

## Timing and Logistics

The Self Qualification Report will be ready on 15-Apr-2014.

The Final PCN is planned to be issued on: 15-Apr-2014.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 12-Mar-2014.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support  
**e-mail address** [DiscrQA.Helpdesk.GA-Products@nxp.com](mailto:DiscrQA.Helpdesk.GA-Products@nxp.com)

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NXP Quality Management Team.

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